



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Apr 12, 2017
Contact Name * Jolene Small	Title - Contact Product Ecology	Phone - Contact * 207-761-6214	Email - Contact * jolene.small@fairchildsemi.com
Authorized Representative * Jolene Small	Title - Representative Product Ecology	Phone - Representative * 207-761-6214	Email - Representative * jolene.small@fairchildsemi.com


Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	FSC Version	Manufacturing Site	Weight*	UOM	Unit Type
FIS1100	FIS1100	LGA-16 (3.3X3.3)	Apr 12, 2017	1.0	ASE KOREA	0.023413	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Precious Metal	Other	3	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above	Supplier Acceptance * Accepted
<p>Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p>		
<p>Exemption List Version EL-2011/534/EU none</p>		

Declaration Signature	
Supplier Signature	 JOLENE SMALL – PRODUCT ECOLOGY ENGINEER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name LGA-16 (3.3X3.3).csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	6.307	Supplier	-	Silicon	6.30731	7440-21-3	269393
Die Attach	Epoxy	0.314	Supplier	-	Acrylic Resin	0.047025	9063-87-0	2008
			Supplier	-	Epoxy Resin	0.266475	29690-82-2	11381
Encapsulation	Thermoplastics	12.956	Supplier	-	Carbon Black	0.06478	1333-86-4	2767
			Supplier	-	Epoxy Resin	0.84214	29690-82-2	35969
			Supplier	-	Phenolic resin (in MC)	0.6478	9003-35-4	27668
			Supplier	-	Silica, vitreous	11.40128	60676-86-0	486964
Plating	Nickel & its alloys	0.074	Supplier	-	Gold	0.01030848	7440-57-5	440
			B	Nickel (external applications only)	Nickel	0.06405984	7440-02-0	2736
Substrate	Other Organic Materials	3.681	Supplier	-	Copper	1.65645	7440-50-8	70749
			Supplier	-	Fibrous glass	1.1043	65997-17-3	47166
			Supplier	-	Phenolic resin (in MC)	0.92025	9003-35-4	39305
Wire Bond	Gold & its alloys	0.081	Supplier	-	Gold	0.08106	7440-57-5	3462